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Applicant: Mui, et al.
Title: METHOD FOR CONTROLLING
CRITICAL DIMENSIONS DURING AN

ETCH PROCESS
Docket: 8377/ETCH/SILICON/JB

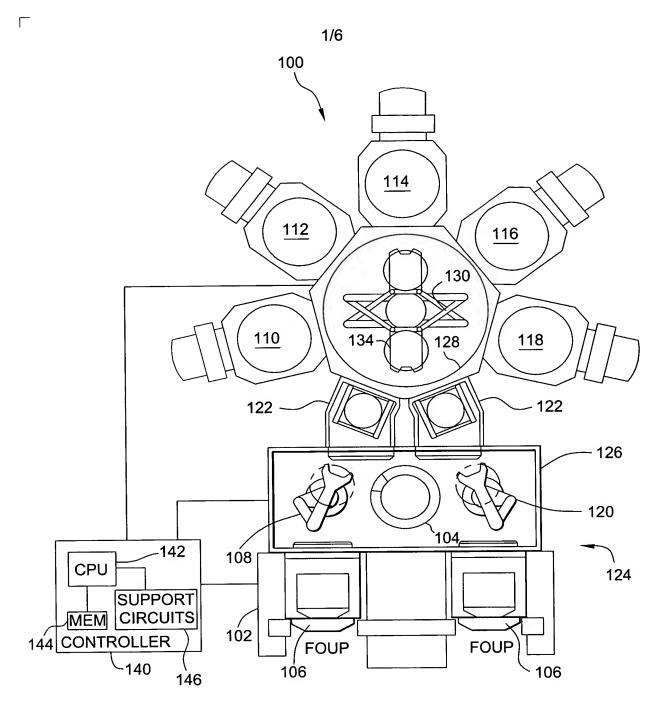


FIG. 1

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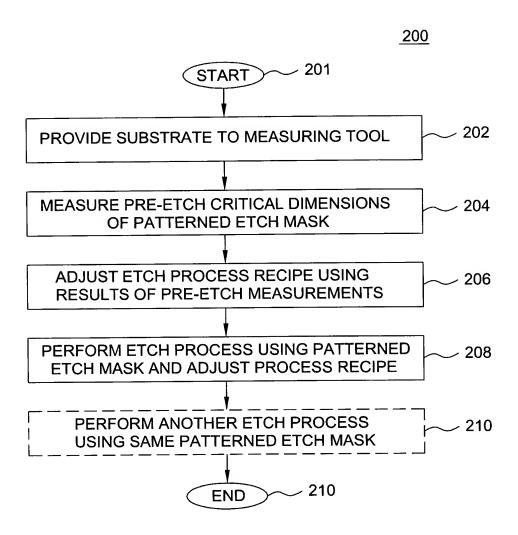


FIG. 2

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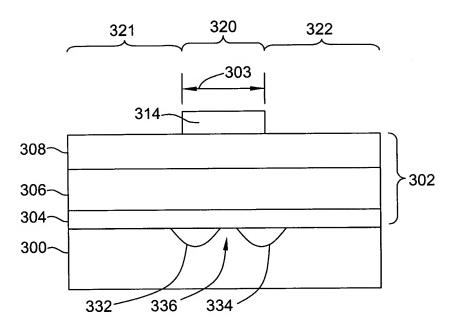


FIG. 3A

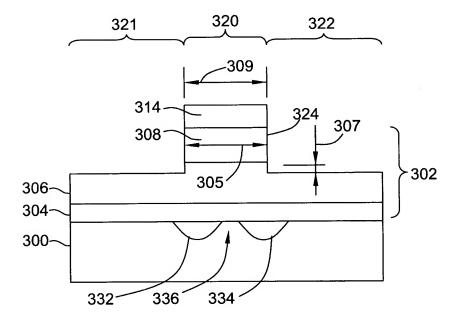


FIG. 3B

 $\Gamma$ 

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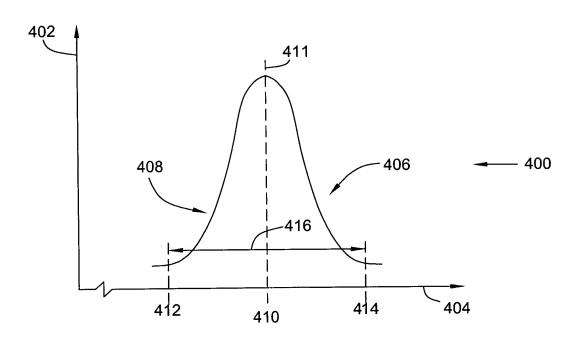


FIG. 4A

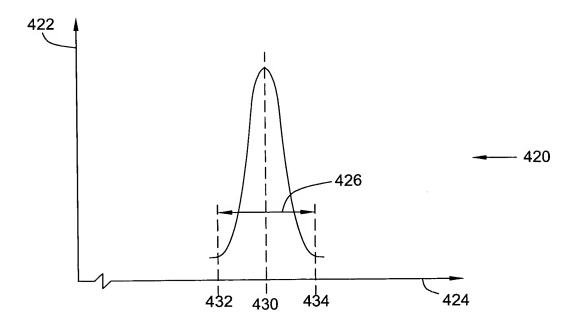
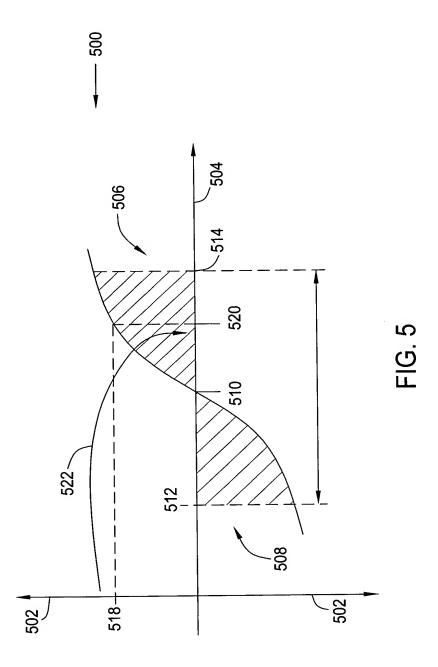


FIG. 4B

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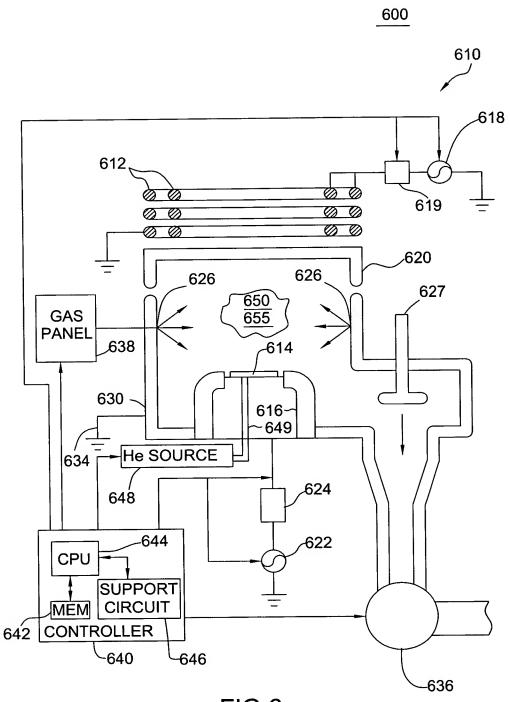


FIG.6